

STARPOWER

SEMICONDUCTOR

MOSFET

MD80HCN500B3S

500V/80A 4 in one-package

General Description

STARPOWER MOSFET Power Module provides very low $R_{DS(on)}$ as well as optimized intrinsic diode. It's designed for the applications such SMPS and DC drives.

Features

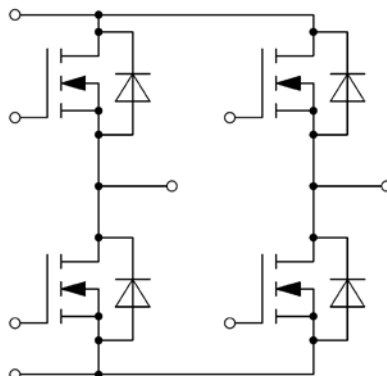
- Low $R_{DS(on)}$
- Optimized intrinsic reverse diode
- Low inductance case avoid oscillations
- Kelvin source terminals for easy drive
- Isolated copper baseplate using DBC technology



Typical Applications

- Main and auxiliary AC drives of electric vehicles
- DC servo and robot drives
- Battery vehicles
- UPS equipment
- Plasma cutting

Equivalent Circuit Schematic



Absolute Maximum Ratings $T_C=25^{\circ}\text{C}$ unless otherwise noted**MOSFET**

Symbol	Description	Value	Unit
V_{DSS}	Drain-Source Voltage	500	V
V_{GSS}	Gate-Source Voltage	± 30	V
I_D	Drain Current @ $T_C=25^{\circ}\text{C}$	80	A
	@ $T_C=100^{\circ}\text{C}$	52	A
I_{DM}	Pulsed Drain Current	200	A
P_D	Maximum Power Dissipation @ $T_j=150^{\circ}\text{C}$	661	W

Inverse Diode

Symbol	Description	Value	Unit
I_S	Source Current	80	A
I_{SM}	Pulsed Source Current	200	A

Module

Symbol	Description	Value	Unit
T_{jmax}	Maximum Junction Temperature	150	$^{\circ}\text{C}$
T_{jop}	Operating Junction Temperature	-40 to +125	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^{\circ}\text{C}$
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	4000	V
M	Terminal Connection Torque, Screw M6	2.5 to 5.0	N.m
	Mounting Torque, Screw M6	3.0 to 5.0	

MOSFET Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$R_{DS(on)}$	Static Drain-Source On-Resistance	$I_D=40\text{A}, V_{GS}=10\text{V}, T_j=25^\circ\text{C}$			32.5	$\text{m}\Omega$
$V_{GS(th)}$	Gate-Source Threshold Voltage	$I_D=8.0\text{mA}, V_{DS}=V_{GS}, T_j=25^\circ\text{C}$	3.0		5.0	V
g_{fs}	Forward Transconductance	$V_{DS}=20\text{V}, I_D=40\text{A}$	45	70		S
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=V_{DSS}, V_{GS}=0\text{V}, T_j=25^\circ\text{C}$			25	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=V_{GSS}, V_{DS}=0\text{V}, T_j=25^\circ\text{C}$			200	nA
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=25\text{V}, f=1.0\text{MHz}$		12.7		nF
C_{oss}	Output Capacitance			1.28		nF
C_{rss}	Reverse Transfer Capacitance			0.12		nF
Q_g	Total Gate Charge	$I_D=40\text{A}, V_{DS}=250\text{V}, V_{GS}=10\text{V}$		197		nC
Q_{gs}	Gate-Source Charge			70		nC
Q_{gd}	Gate-Drain ("Miller") Charge			64		nC
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=250\text{V}, I_D=40\text{A}, R_G=1.0\Omega, V_{GS}=10\text{V}, T_j=25^\circ\text{C}$		25		ns
t_r	Rise Time			27		ns
$t_{d(off)}$	Turn-Off Delay Time			70		ns
t_f	Fall Time			16		ns

Inverse Diode Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{SD}	Diode Forward Voltage	$I_S=80\text{A}, V_{GS}=0\text{V}, T_j=25^\circ\text{C}$			1.50	V
t_{rr}	Diode Reverse Recovery Time	$V_R=100\text{V}, I_F=25\text{A}, -di/dt=100\text{A}/\mu\text{s}, T_j=25^\circ\text{C}, V_{GS}=0\text{V}$			200	ns
I_{RM}	Peak Reverse Recovery Current			6		A
Q_r	Diode Reverse Recovery Charge			0.6		μC

Module Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
$R_{\theta JC}$	Junction-to-Case(Mosfet)			0.189	K/W
$R_{\theta CS}$	Case-to-Sink(Mosfet)		0.140		K/W
$R_{\theta CS}$	Case-to-Sink		0.035		K/W
G	Weight of Module		300		g

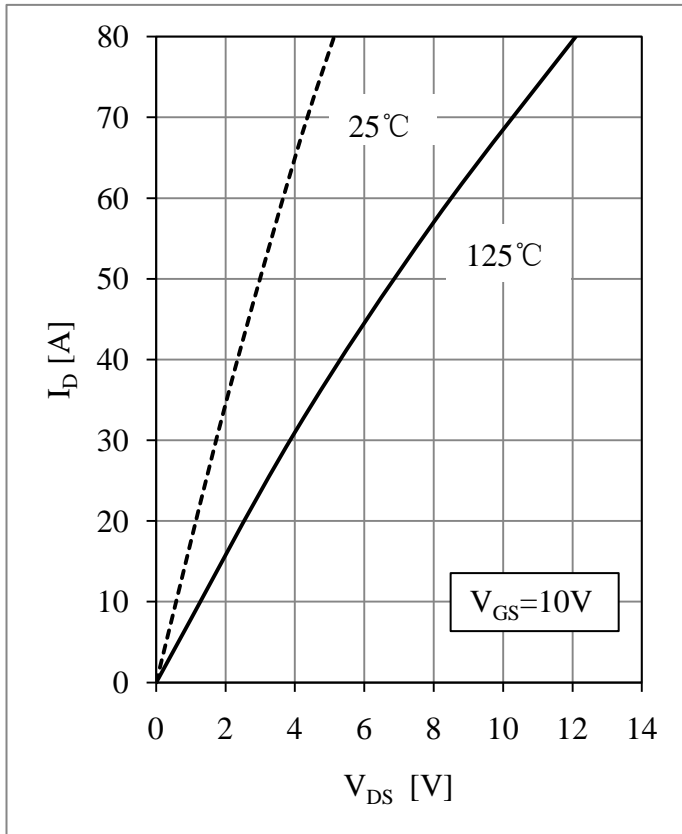


Fig 1. Mosfet Output Characteristics

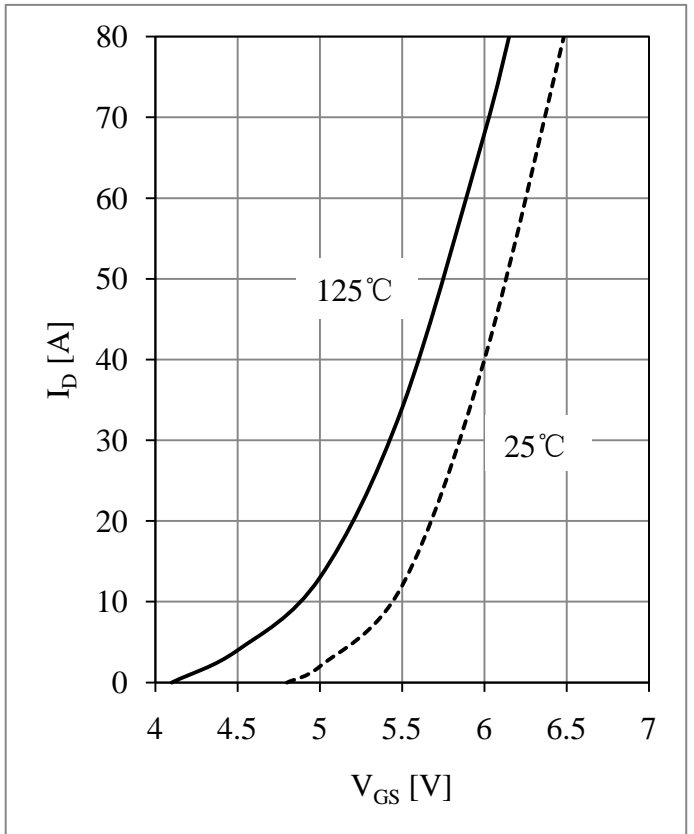


Fig 2. Mosfet Transfer Characteristics

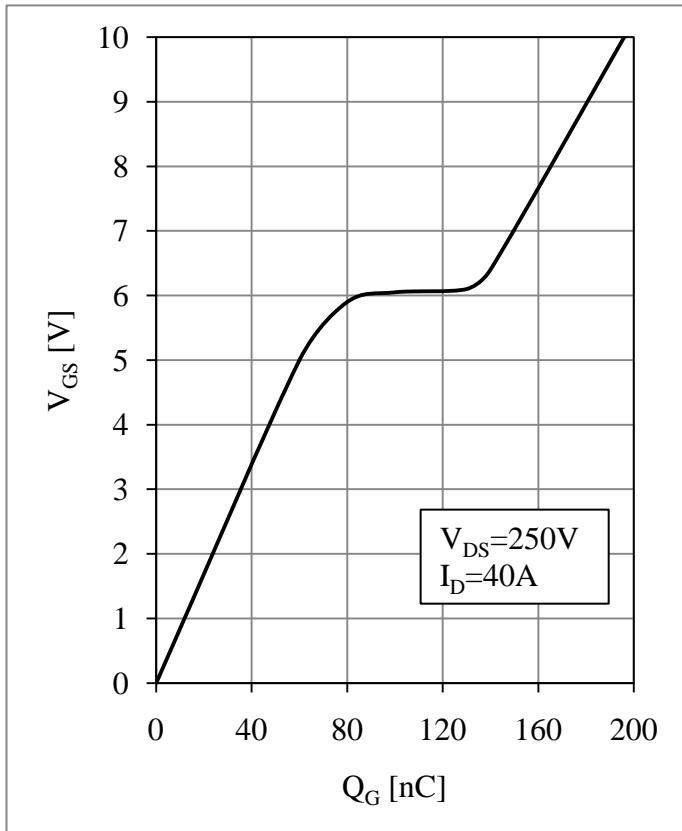


Fig 3. Gate Charge Characteristic

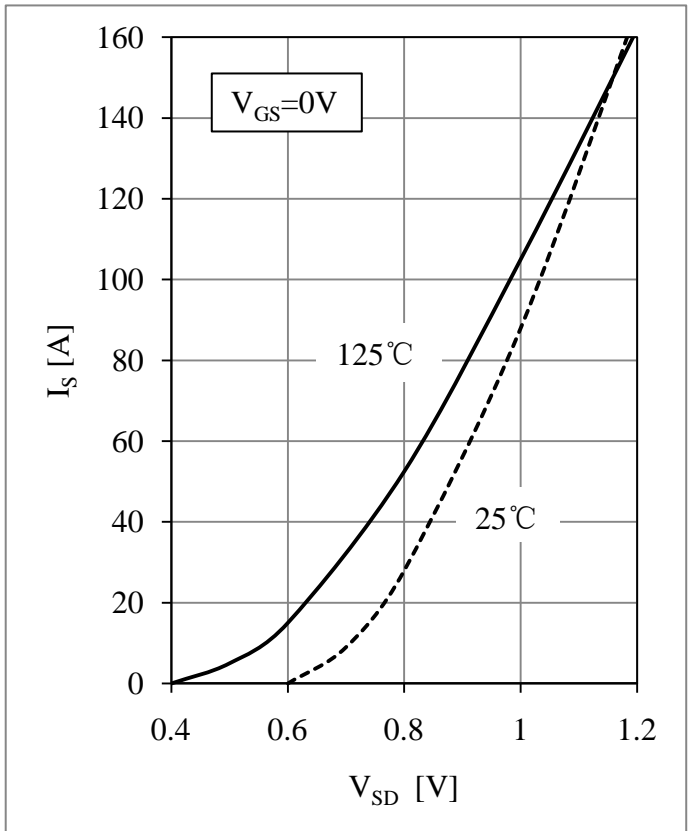


Fig 4. Inverse Diode Output Characteristics

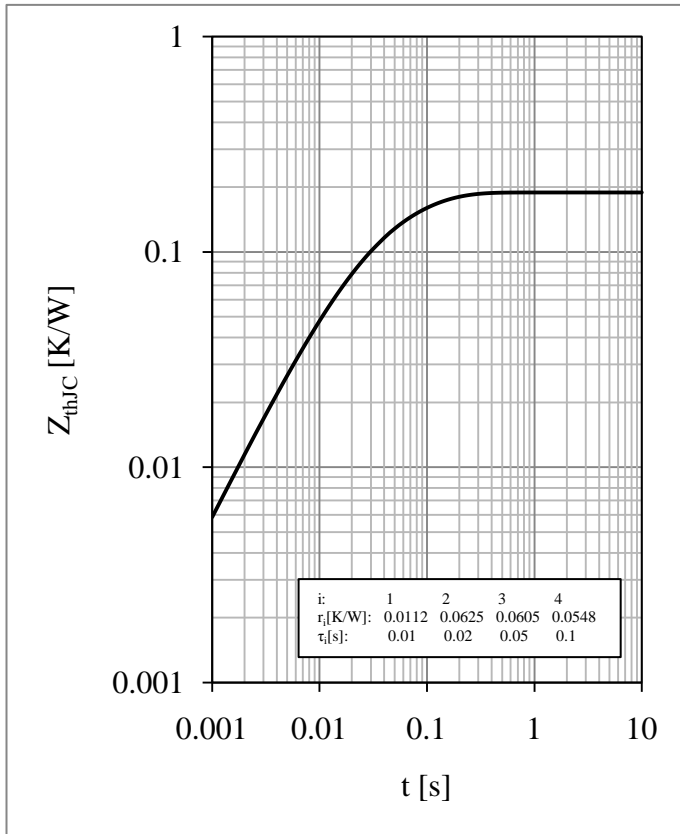
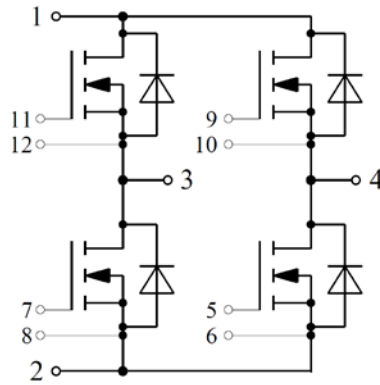


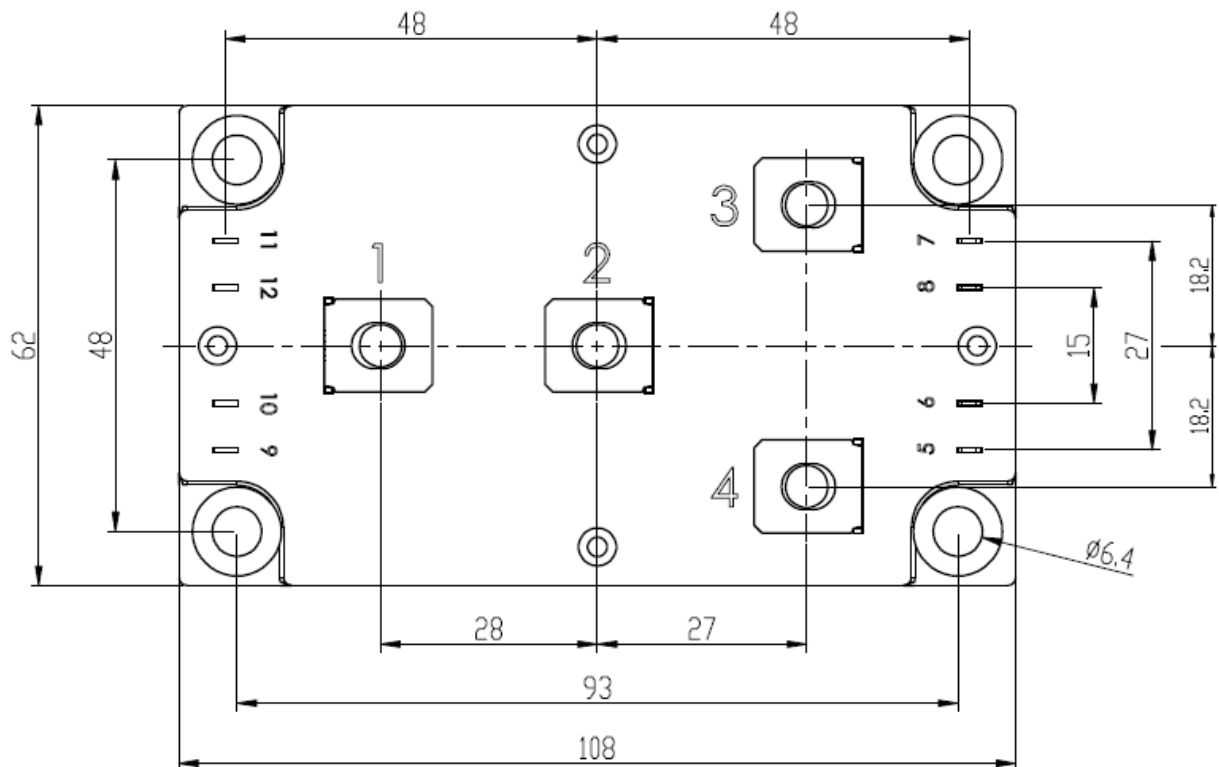
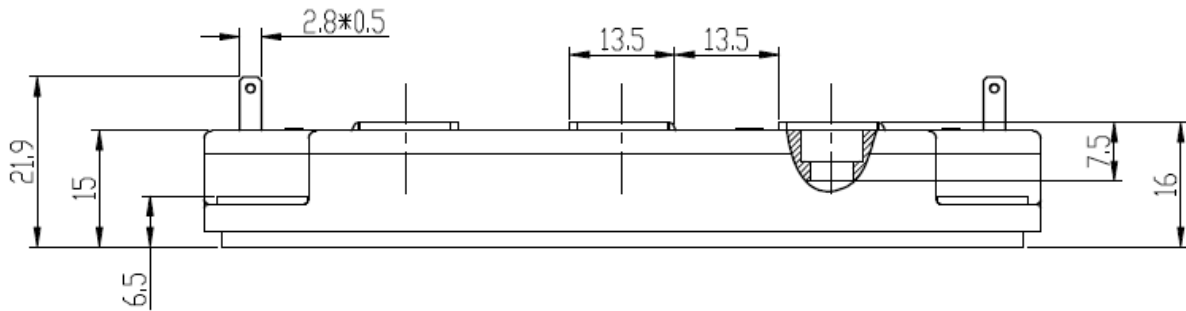
Fig 5. Transient Thermal Impedance

Circuit Schematic



Package Dimensions

Dimensions in Millimeters



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